

TITLE OF THE INVENTION

SEMICONDUCTOR DEVICE ASSEMBLIES INCLUDING INTERPOSERS WITH DAMS PROTRUDING THEREFROM

CROSS-REFERENCE TO RELATED APPLICATIONS

[0001] This application is a divisional of application Serial No. 09/864,471, filed May 24, 2001, ^{Pat. 6,531,335} pending, which is a divisional of application Serial No. 09/560,970, filed April 28, 2000, now U.S. Patent 6,531,335, issued March 11, 2003.

BACKGROUND OF THE INVENTION

Field of the Invention

[0002] The present invention relates generally to interposers for use in chip-scale packages (CSPs), including ball grid array (BGA) packages. Particularly, the present invention relates to interposers that include upwardly protruding dams configured to laterally confine encapsulant material over a specified area of the interposer. The invention also relates to semiconductor device packages including the interposers and to methods of fabricating the upwardly protruding dams, the interposers, and assemblies including the interposers.

Background of Related Art

Semiconductor Device Packages

[0003] Semiconductor devices, such as memory devices and processors, are generally fabricated in very large numbers. Typically, several semiconductor devices are fabricated on a wafer or other large-scale substrate that includes a layer of semiconductor material (e.g., silicon, gallium arsenide, or indium phosphide). The semiconductor devices are then singulated, or diced, from the wafer or other large-scale substrate to provide semiconductor "chips" or dice.

[0004] Conventionally, semiconductor dice have been packaged for protection and to facilitate the formation of electrical connections to the small bond pads thereof. Conventional semiconductor device packages typically include an assembly of a semiconductor die and a higher level substrate board (e.g., a circuit board) or leads. Bond pads of the semiconductor die